

2SC5954

Silicon NPN triple diffusion planar type

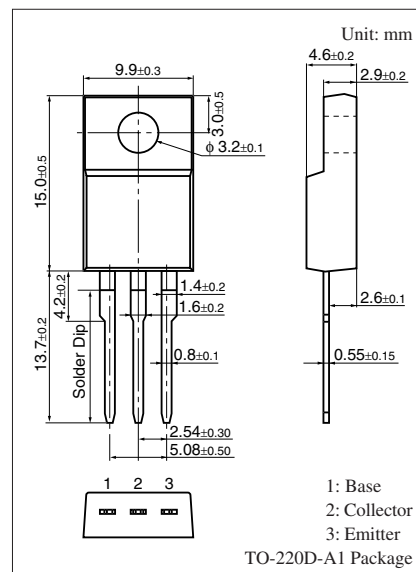
For power amplification with high forward current transfer ratio

■ Features

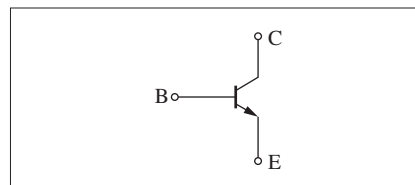
- High forward current transfer ratio h_{FE} which has satisfactory linearity.
- Low collector-emitter saturation voltage $V_{CE(sat)}$
- Full-pack package which can be installed to the heat sink with one screw.

■ Absolute Maximum Ratings $T_C = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V_{CBO}	80	V
Collector-emitter voltage (Base open)	V_{CEO}	60	V
Emitter-base voltage (Collector open)	V_{EBO}	6	V
Collector current	I_C	3	A
Peak collector current	I_{CP}	6	A
Collector power dissipation	P_C	25	W
	$T_a = 25^\circ\text{C}$	2.0	
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$



Internal Connection



■ Electrical Characteristics $T_C = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-emitter voltage (Base open)	V_{CEO}	$I_C = 10\text{ mA}, I_B = 0$	60			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = 80\text{ V}, I_E = 0$			100	μA
Collector-emitter cutoff current (Base open)	I_{CEO}	$V_{CE} = 40\text{ V}, I_B = 0$			100	μA
Emitter-base cutoff current (Collector open)	I_{EBO}	$V_{EB} = 6\text{ V}, I_C = 0$			100	μA
Forward current transfer ratio	h_{FE1} *	$V_{CE} = 4\text{ V}, I_C = 0.5\text{ A}$	500		2300	—
	h_{FE2}	$V_{CE} = 4\text{ V}, I_C = 3\text{ A}$	100			
Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_C = 1\text{ A}, I_B = 20\text{ mA}$			0.6	V
Transition frequency	f_T	$V_{CE} = 10\text{ V}, I_C = 0.1\text{ A}, f = 10\text{ MHz}$		200		MHz
Turn-on time	t_{on}	$I_C = 1\text{ A}, \text{Resistance loaded}$		0.2		μs
Storage time	t_{stg}	$I_{B1} = 0.1\text{ A}, I_{B2} = -0.1\text{ A}$		1.5		μs
Fall time	t_f	$V_{CC} = 50\text{ V}$		0.1		μs

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. *: Rank classification

Rank	Q	P
h_{FE1}	500 to 1500	1300 to 2300

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